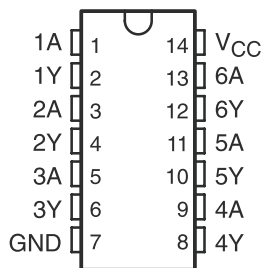


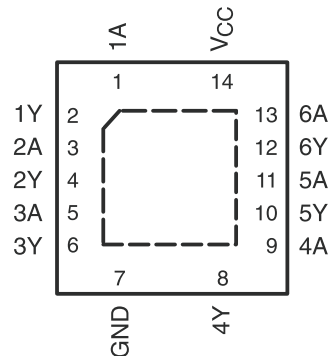
FEATURES

- 2-V to 5.5-V V_{CC} Operation
- Max t_{pd} of 10 ns at 5 V
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) >2.3 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Support Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

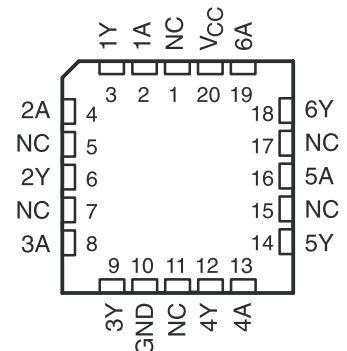
SN54LV14A...J OR W PACKAGE
SN74LV14A...D, DB, DGV, NS
OR PW PACKAGE
(TOP VIEW)



SN74LV14A...RGY PACKAGE
(TOP VIEW)



SN54LV14A...FK PACKAGE
(TOP VIEW)



NC – No internal connection

DESCRIPTION/ORDERING INFORMATION

These hex Schmitt-trigger inverters are designed for 2-V to 5.5-V V_{CC} operation.

The 'LV14A devices contain six independent inverters. These devices perform the Boolean function $Y = \bar{A}$.

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	QFN – RGY	Reel of 1000	SN74LV14ARGYR	LV14A
	SOIC – D	Tube of 50	SN74LV14AD	LV14A
		Reel of 2500	SN74LV14ADR	LV14A
	SOP – NS	Reel of 2000	SN74LV14ANSR	74LV14A
	SSOP – DB	Reel of 2000	SN74LV14ADBR	LV14A
	TSSOP – PW	Tube of 90	SN74LV14APW	LV14A
		Reel of 2000	SN74LV14APWR	LV14A
Reel of 250		SN74LV14APWT	LV14A	
TVSOP – DGV	Reel of 2000	SN74LV14ADGVR	LV14A	
–55°C to 125°C	CDIP – J	Tube of 25	SNJ54LV14AJ	SNJ54LV14AJ
	CFP – W	Tube of 150	SNJ54LV14AW	SNJ54LV14AW
	LCCC – FK	Tube of 55	SNJ54LV14AFK	SNJ54LV14AFK

(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.

(2) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

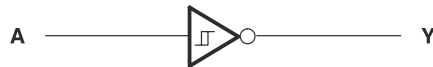
SN54LV14A, SN74LV14A HEX SCHMITT-TRIGGER INVERTERS

SCLS386 J—SEPTEMBER 1997—REVISED APRIL 2005

**FUNCTION TABLE
(each inverter)**

INPUT A	OUTPUT Y
H	L
L	H

LOGIC DIAGRAM, EACH INVERTER (POSITIVE LOGIC)



ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	7	V
V_I	Input voltage range ⁽²⁾	-0.5	7	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	7	V
V_O	Output voltage range ⁽²⁾⁽³⁾	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$		-20 mA
I_{OK}	Output clamp current	$V_O < 0$		-50 mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}		± 25 mA
Continuous current through V_{CC} or GND				± 50 mA
θ_{JA}	Package thermal impedance	D package ⁽⁴⁾		86
		DB package ⁽⁴⁾		96
		DGV package ⁽⁴⁾		127
		NS package ⁽⁴⁾		76
		PW package ⁽⁴⁾		113
		RGY package ⁽⁵⁾		47
T_{stg}	Storage temperature range	-65	150	$^{\circ}\text{C}$

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 5.5 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-7
- (5) The package thermal impedance is calculated in accordance with JESD 51-5.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

		SN54LV14A ⁽²⁾		SN74LV14A		UNIT
		MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage	2	5.5	2	5.5	V
V_I	Input voltage	0	5.5	0	5.5	V
V_O	Output voltage	0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 2\text{ V}$		-50	-50	μA
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		-2	-2	mA
		$V_{CC} = 3\text{ V to }3.6\text{ V}$		-6	-6	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		-12	-12	
I_{OL}	Low-level output current	$V_{CC} = 2\text{ V}$		50	50	μA
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		2	2	mA
		$V_{CC} = 3\text{ V to }3.6\text{ V}$		6	6	
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$		12	12	
T_A	Operating free-air temperature	-55	125	-40	85	$^{\circ}\text{C}$

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

(2) Product Preview

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	SN54LV14A ⁽¹⁾			SN74LV14A			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{T+} Positive-going threshold		2.5 V	1.75			1.75			V
		3.3 V	2.31			2.31			
		5 V	3.5			3.5			
V_{T-} Negative-going threshold		2.5 V	0.75			0.75			V
		3.3 V	0.99			0.99			
		5 V	1.5			1.5			
ΔV_T Hysteresis ($V_{T+} - V_{T-}$)		2.5 V	0.25			0.25			V
		3.3 V	0.33			0.33			
		5 V	0.5			0.5			
V_{OH}	$I_{OH} = -50\ \mu\text{A}$	2 V to 5.5 V	$V_{CC} - 0.1$			$V_{CC} - 0.1$			V
	$I_{OH} = -2\ \text{mA}$	2.3 V	2			2			
	$I_{OH} = -6\ \text{mA}$	3 V	2.48			2.48			
	$I_{OH} = -12\ \text{mA}$	4.5 V	3.8			3.8			
V_{OL}	$I_{OL} = 50\ \mu\text{A}$	2 V to 5.5 V	0.1			0.1			V
	$I_{OL} = 2\ \text{mA}$	2.3 V	0.4			0.4			
	$I_{OL} = 6\ \text{mA}$	3 V	0.44			0.44			
	$I_{OL} = 12\ \text{mA}$	4.5 V	0.55			0.55			
I_I	$V_I = V_{CC}$ or GND	0 to 5.5 V	± 1			± 1			μA
I_{CC}	$V_I = V_{CC}$ or GND, $I_O = 0$	5.5 V	20			20			μA
I_{off}	V_I or $V_O = 0$ to 5.5 V	0	5			5			μA
C_i	$V_I = V_{CC}$ or GND	3.3 V	2.3			2.3			pF
		5 V	2.3			2.3			

(1) Product Preview

SN54LV14A, SN74LV14A HEX SCHMITT-TRIGGER INVERTERS

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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV14A ⁽¹⁾		SN74LV14A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	Y	$C_L = 15\text{ pF}$	10.2 ⁽²⁾	19.7 ⁽²⁾	1 ⁽²⁾	22 ⁽²⁾	1	22	ns	
			$C_L = 50\text{ pF}$	13.3	24	1	27	1	27		

(1) Product Preview

(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV14A ⁽¹⁾		SN74LV14A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	Y	$C_L = 15\text{ pF}$	7.3 ⁽²⁾	12.8 ⁽²⁾	1 ⁽²⁾	15.9 ⁽²⁾	1	15	ns	
			$C_L = 50\text{ pF}$	9.6	16.3	1	19.4	1	18.5		

(1) Product Preview

(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			SN54LV14A ⁽¹⁾		SN74LV14A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A	Y	$C_L = 15\text{ pF}$	5.1 ⁽²⁾	8.6 ⁽²⁾	1 ⁽²⁾	10 ⁽²⁾	1	10	ns	
			$C_L = 50\text{ pF}$	6.7	10.6	1	12	1	12		

(1) Product Preview

(2) On products compliant to MIL-PRF-38535, this parameter is not production tested.

NOISE CHARACTERISTICS

$V_{CC} = 3.3\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ ⁽¹⁾

		SN74LV14A			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic		0.2	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic		-0.1	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic		3.1		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage		0.99		V

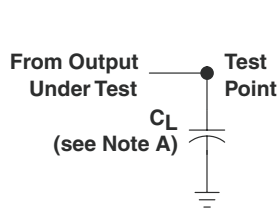
(1) Characteristics are for surface-mount packages only.

OPERATING CHARACTERISTICS

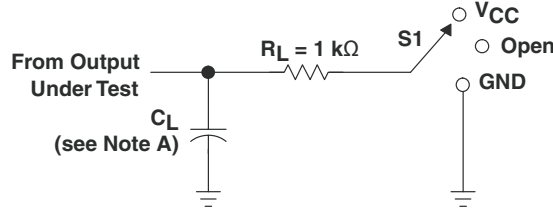
$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50\text{ pF}$, $f = 10\text{ MHz}$	3.3 V	8.8	pF
			5 V	9.6	

PARAMETER MEASUREMENT INFORMATION

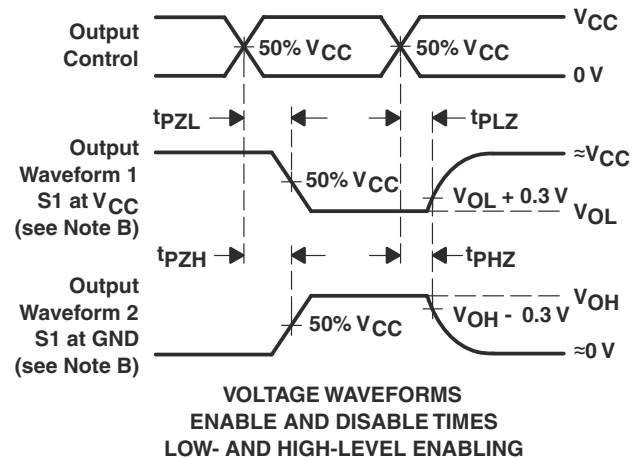
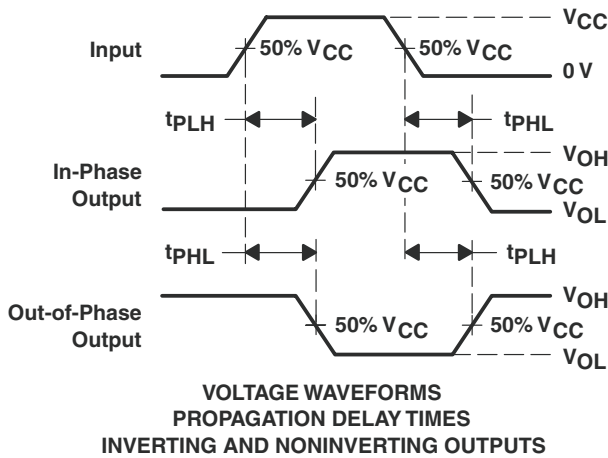
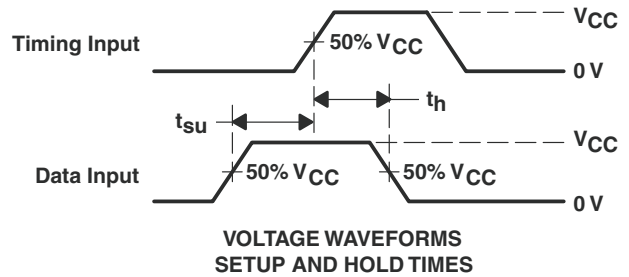
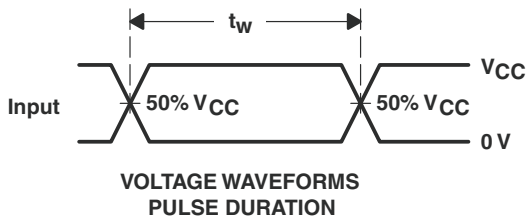


LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS



LOAD CIRCUIT FOR 3-STATE AND OPEN-DRAIN OUTPUTS

TESTS1	
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{CC}
t _{PHZ} /t _{PZH}	GND
Open Drain	V _{CC}



- A. C_L includes probe and jig capacitance.
- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
- D. The outputs are measured one at a time, with one input transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PHL} and t_{PLH} are the same as t_{pd}.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV14AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ADBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI
SN74LV14ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ADGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ADGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ADGVRG4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74LV14APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV14APWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
SN74LV14ARGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
SN74LV14ARGYRG4	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LV14A :

- Automotive: [SN74LV14A-Q1](#)
- Enhanced Product: [SN74LV14A-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV14ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74LV14ADGVR	TVSOP	DGV	14	2000	330.0	12.4	6.8	4.0	1.6	8.0	12.0	Q1
SN74LV14ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV14ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74LV14ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LV14APWR	TSSOP	PW	14	2000	330.0	12.4	7.0	5.6	1.6	8.0	12.0	Q1
SN74LV14ARGYR	QFN	RGY	14	1000	180.0	12.4	3.85	3.85	1.35	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV14ADBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74LV14ADGVR	TVSOP	DGV	14	2000	346.0	346.0	29.0
SN74LV14ADR	SOIC	D	14	2500	333.2	345.9	28.6
SN74LV14ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74LV14ANSR	SO	NS	14	2000	346.0	346.0	33.0
SN74LV14APWR	TSSOP	PW	14	2000	346.0	346.0	29.0
SN74LV14ARGYR	QFN	RGY	14	1000	190.5	212.7	31.8

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

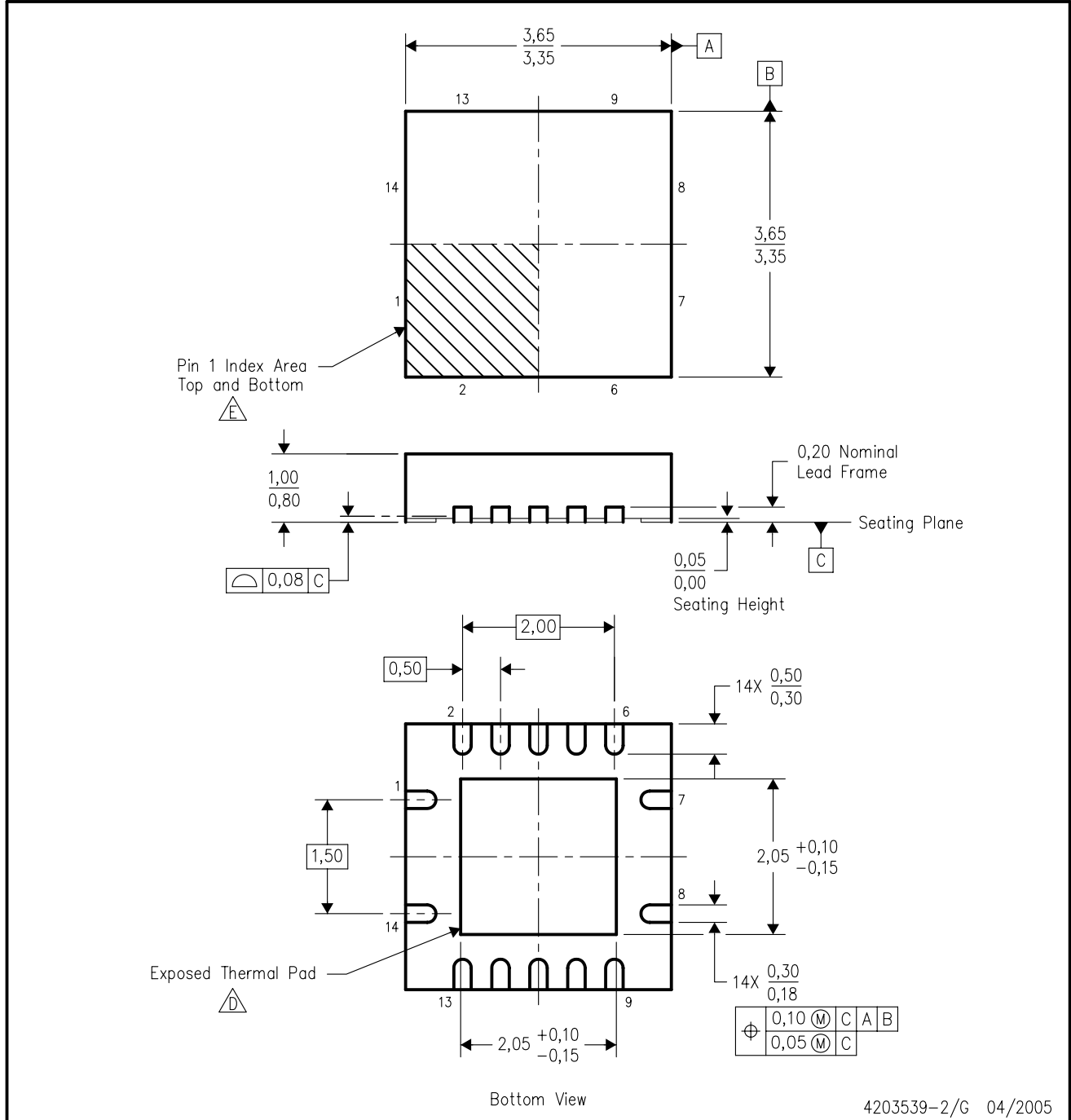
24 PINS SHOWN





- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

RGY (S-PQFP-N14)

PLASTIC QUAD FLATPACK



4203539-2/G 04/2005

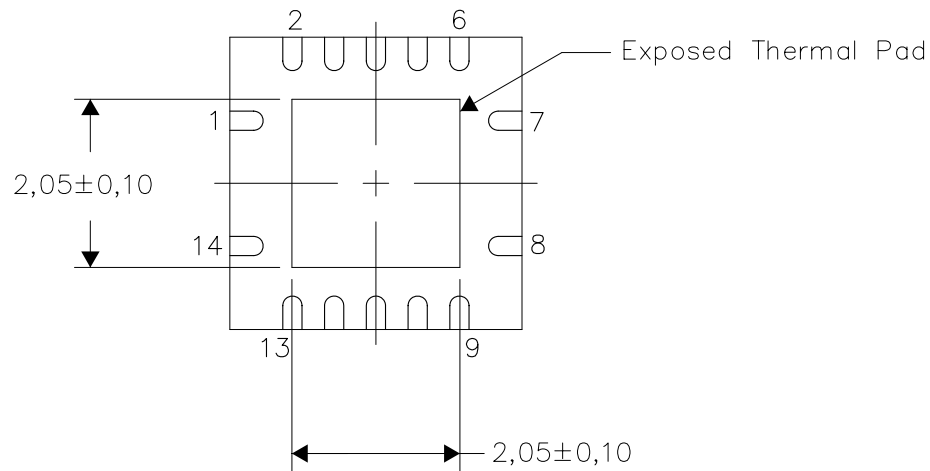
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 -  The package thermal pad must be soldered to the board for thermal and mechanical performance.
 -  Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - F. Package complies to JEDEC MO-241 variation BA.

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, Quad Flatpack No-Lead Logic Packages, Texas Instruments Literature No. SCBA017. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.

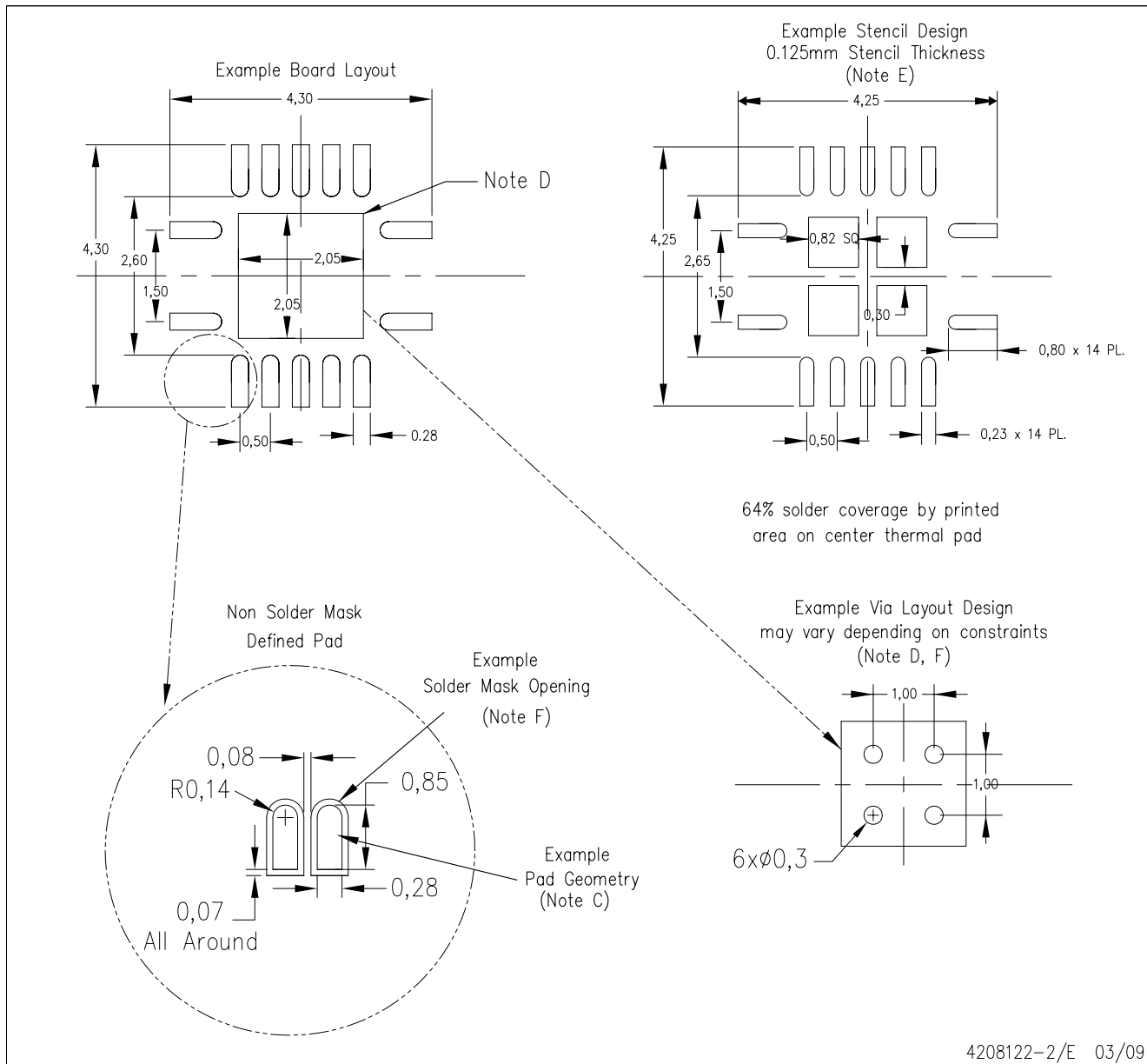


Bottom View

NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

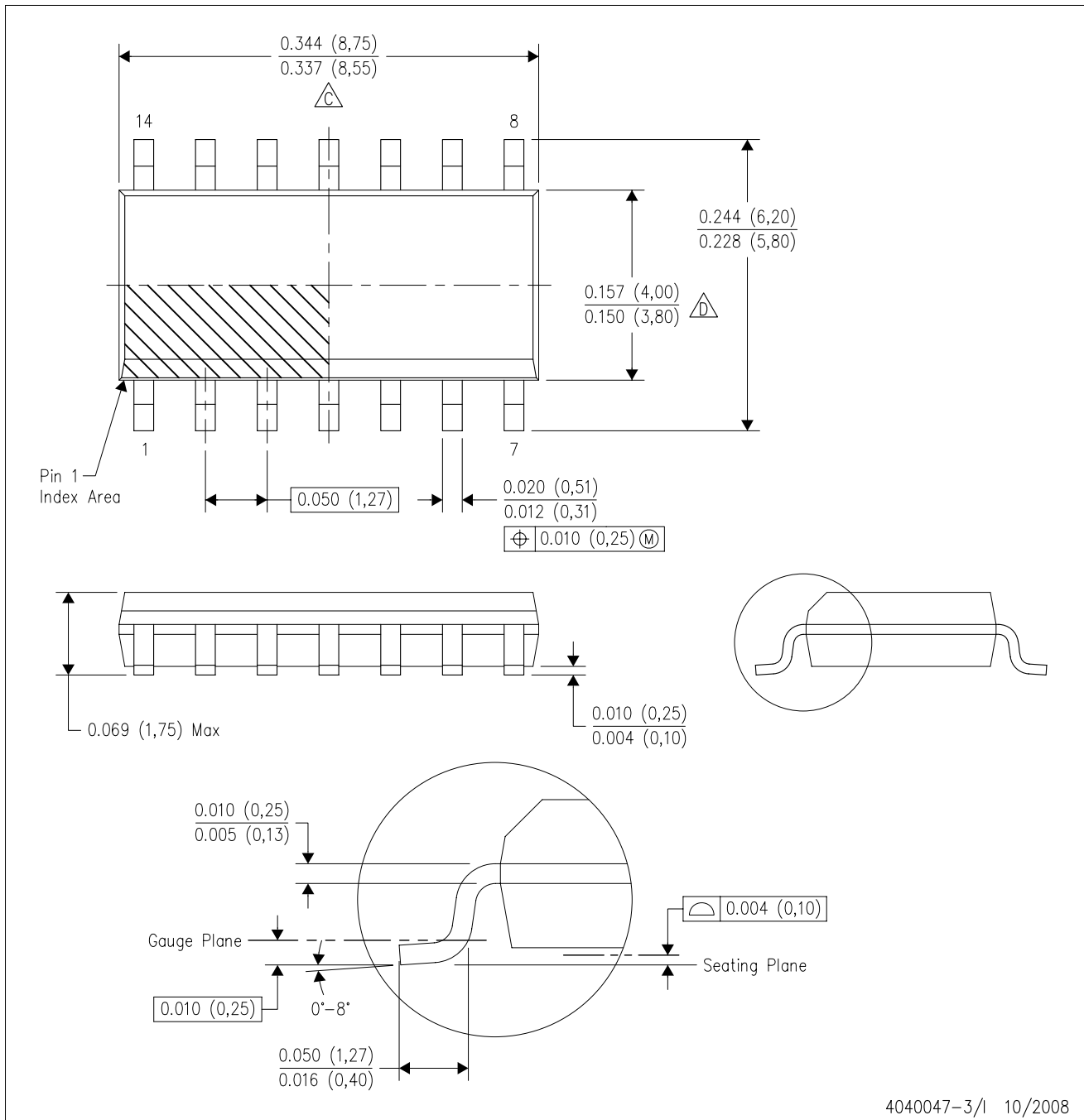
RGY (S-PVQFN-N14)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AB.

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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